Page 1 of 2

SCHEPARTMENT OF COMMERCE SERIAL NO. Form PTO-1449 ATTY, DOCKET NO. PATENT AND TRADEMARK OFFICE (MODIFIED) 10/008,591 QUANT1350 (028248-2301) APPLICANT INFORMATION DISCLOSURE CITATION Dershem et al. PADEMA **GROUP ART UNIT** FILING DATE (Use several sheets if necessary) 11/13/2001 1624 **U.S. PATENT DOCUMENTS** FILING DATE DOCUMENT SUB-**EXAMINER CLASS** DATE NAME REF **CLASS** INITIAL NUMBER **APPROPRIATE** Α1 4,607,091 8-19-86 Schreiber 528 96 RR RECEIVED 100 5,021,484 6-4-91 Schreiber et al. 524 A2 RR 524 398 5,200,452 4-6-93 Schreiber А3 RR JUN 1 9 2002 Schreiber et al. 428 413 5,443,911 8-22-95 A4 RR TECH CENTER 1600/2900 5,447,988 9-5-95 Dershem et al. 524 780 A5 RR 69 8-6-96 Ishida 544 5,543,516 A6 RR Dershem et al. 526 262 6,034,194 3-7-00 **A7** RR 3-7-00 Dershem et al. 526 262 **A8** 6,034,195 RR 528 94 6,207,786 B1 3-27-01 Ishida et al. Α9 FOREIGN PATENT DOCUMENTS TRANSLATION **DOCUMENT** SUB-**REF** DATE COUNTRY **CLASS** NUMBER CLASS YES NO OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) Dagani, "Novel Water-displacing Polymers Show Promise in Coating Uses," C&EN, July 29, 1991, p. 20-22. nr A10 Ishida, "Development of Polybenzoxazines: A New Class of High Performance, Ring-Opening Phenolic Resins RP A11 With Superb Balance..." Proceedings of the International Composites Expo, 1998, Session 14-B, p. 1-8. Ishida et al., "Synthesis of Benzoxazine Functional Silane and Adhesion Properties of Glass-Fiber-Reinforced RP A12 Polybenzoxazine Composites," Journal of Applied Polymer Science, Vol. 69, 1998, p. 2559-2567. Kimura, "New Thermosetting Resin From Bisphenol A-Based Benzoxazine and Bisoxazoline," Journal of VM A13 Applied Polymer Science, Vol. 72, 1999, p. 1551-1554. Liang et al, "Amine-Quinone Polyurethanes as Binders for Metal Particle Tape," IEEE Transactions on RK A14 Magnetics, Vol. 29, No. 6, 1993, p. 3649-3651. **EXAMINER** DATE CONSIDERED 8-2-03 EXAMINER: Initial if citation c nsidered, whether or not citation is in conformance with MPEP 609; Draw

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